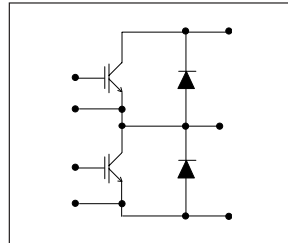


Features

- UltraFast Non Punch Through (NPT) Technology
- Positive $V_{CE(ON)}$ Temperature Coefficient
- 10 μ s Short Circuit Capability
- HEXFRED™ Antiparallel Diodes with UltraSoft Reverse Recovery
- Low Diode V_F
- Square RBSOA
- Aluminum Nitride DBC
- Optional SMT Thermistor (NTC)
- Very Low Stray Inductance Design for High Speed Operation
- UL approved (file E78996)



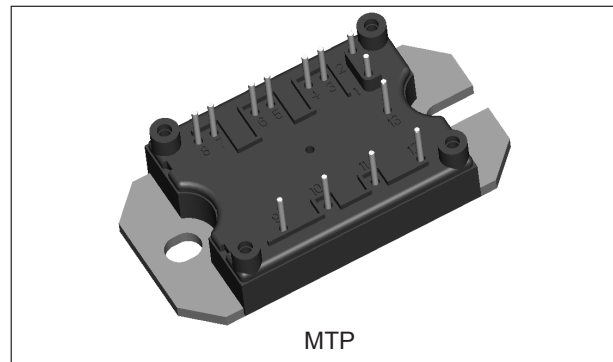
$$V_{CES} = 1200V$$

$$I_C = 80A$$

$$T_C = 25^{\circ}C$$

Benefits

- Optimized for Welding, UPS and SMPS Applications
- Rugged with UltraFast Performance
- Benchmark Efficiency above 20KHz
- Outstanding ZVS and Hard Switching Operation
- Low EMI, requires Less Snubbing
- Excellent Current Sharing in Parallel Operation
- Direct Mounting to Heatsink
- PCB Solderable Terminals



Absolute Maximum Ratings

| Parameters | Max | Units | |
|---|------------------------|-------|----|
| V_{CES} Collector-to-Emitter Breakdown Voltage | 1200 | V | |
| I_C Continuous Collector Current | @ $T_C = 25^{\circ}C$ | 80 | |
| | @ $T_C = 105^{\circ}C$ | 40 | |
| I_{CM} Pulsed Collector Current | 160 | A | |
| I_{LM} Clamped Inductive Load Current | 160 | | |
| I_F Diode Continuous Forward Current | @ $T_C = 105^{\circ}C$ | | 21 |
| I_{FM} Diode Maximum Forward Current | 160 | | |
| V_{GE} Gate-to-Emitter Voltage | ± 20 | | V |
| V_{ISOL} RMS Isolation Voltage, Any Terminal to Case, $t = 1$ min | 2500 | | |
| P_D Maximum Power Dissipation (only IGBT) | @ $T_C = 25^{\circ}C$ | 463 | |
| | @ $T_C = 100^{\circ}C$ | 185 | |
| | | W | |

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

| Parameters | Min | Typ | Max | Units | Test Conditions | |
|--|------|------|------|-------|--|---|
| V _{(BR)CES} Collector-to-Emitter Breakdown Voltage | 1200 | | | V | V _{GE} = 0V, I _C = 250μA | |
| ΔV _{(BR)CES} /ΔT _J Temperature Coeff. of Breakdown Voltage | | +1.1 | | V/°C | V _{GE} = 0V, I _C = 3mA (25-125°C) | |
| V _{CE(ON)} Collector-to-Emitter Saturation Voltage | | 3.36 | 3.59 | V | V _{GE} = 15V, I _C = 40A | |
| | | 4.53 | 4.91 | | V _{GE} = 15V, I _C = 80A | |
| | | 3.88 | 4.10 | | V _{GE} = 15V, I _C = 40A T _J = 150°C | |
| | | 5.35 | 5.68 | | V _{GE} = 15V, I _C = 80A T _J = 150°C | |
| V _{GE(th)} Gate Threshold Voltage | 4 | | 6 | V | V _{CE} = V _{GE} , I _C = 500μA | |
| ΔV _{GE(th)} /ΔT _J Temperature Coeff. of Threshold Voltage | | -12 | | mV/°C | V _{CE} = V _{GE} , I _C = 1mA (25-125°C) | |
| g _{fe} Transconductance | | 35 | | S | V _{CE} = 50V, I _C = 40A, PW = 80μs | |
| I _{CES} Zero Gate Voltage Collector Current | | | 250 | μA | V _{GE} = 0V, V _{CE} = 1200V, T _J = 25°C | |
| | | | 0.4 | 1.0 | mA | V _{GE} = 0V, V _{CE} = 1200V, T _J = 125°C |
| | | | 0.2 | 10 | | V _{GE} = 0V, V _{CE} = 1200V, T _J = 150°C |
| I _{GES} Gate-to-Emitter Leakage Current | | | ±250 | nA | V _{GE} = ± 20V | |

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

| Parameters | Min | Typ | Max | Units | Test Conditions |
|---|-------------|------|------|-------|--|
| Q _g Total Gate Charge (turn-on) | | 399 | 599 | nC | I _C = 40A V _{CC} = 600V V _{GE} = 15V |
| Q _{ge} Gate-Emitter Charge (turn-on) | | 43 | 65 | | |
| Q _{gc} Gate-Collector Charge (turn-on) | | 187 | 281 | | |
| E _{on} Turn-On Switching Loss | | 1142 | 1713 | μJ | V _{CC} = 600V, I _C = 40A V _{GE} = 15V, R _g = 5Ω, L = 200μH T _J = 25°C, Energy losses include tail and diode reverse recovery |
| E _{off} Turn-Off Switching Loss | | 1345 | 2018 | | |
| E _{tot} Total Switching Loss | | 2487 | 3731 | | |
| E _{on} Turn-On Switching Loss | | 1598 | 2397 | | |
| E _{off} Turn-Off Switching Loss | | 1618 | 2427 | μJ | V _{CC} = 600V, I _C = 40A V _{GE} = 15V, R _g = 5Ω, L = 200μH T _J = 125°C, Energy losses include tail and diode reverse recovery |
| E _{tot} Total Switching Loss | | 3216 | 4824 | | |
| E _{tot} Total Switching Loss | | 3216 | 4824 | | |
| C _{ies} Input Capacitance | | 5521 | 8282 | pF | V _{GE} = 0V V _{CC} = 30V f = 1.0 MHz |
| C _{oes} Output Capacitance | | 380 | 570 | | |
| C _{res} Reverse Transfer Capacitance | | 171 | 257 | | |
| RBSOA Reverse Bias Safe Operating Area | full square | | | | T _J = 150°C, I _C = 160A V _{CC} = 1000V, V _p = 1200V R _g = 5Ω, V _{GE} = +15V to 0V |
| SCSOA Short Circuit Safe Operating Area | 10 | | | μs | T _J = 150°C V _{CC} = 900V, V _p = 1200V R _g = 5Ω, V _{GE} = +15V to 0V |

Diode Characteristics @ T_J = 25°C (unless otherwise specified)

| Parameters | Min | Typ | Max | Units | Test Conditions |
|---|-----|------|------|-------|---|
| V _{FM} Diode Forward Voltage Drop | | 2.98 | 3.38 | V | I _C = 40A |
| | | 3.90 | 4.41 | | I _C = 80A |
| | | 3.08 | 3.39 | | I _C = 40A, T _J = 125°C |
| | | 4.29 | 4.72 | | I _C = 80A, T _J = 125°C |
| | | 3.12 | 3.42 | | I _C = 40A, T _J = 150°C |
| E _{rec} Reverse Recovery Energy of the Diode | | 574 | 861 | μJ | V _{GE} = 15V, R _g = 5Ω, L = 200μH |
| t _{rr} Diode Reverse Recovery Time | | 120 | 180 | ns | V _{CC} = 600V, I _C = 40A |
| I _{rr} Peak Reverse Recovery Current | | 43 | 65 | A | T _J = 125°C |

Thermistor Specifications (40MT120UHT only)

| Parameters | Min | Typ | Max | Units | Test Conditions |
|--|-----|------|-----|-------|--|
| R ₀ ⁽¹⁾ Resistance | | 30 | | kΩ | T ₀ = 25°C |
| β ⁽¹⁾⁽²⁾ Sensitivity index of the thermistor material | | 4000 | | K | T ₀ = 25°C T ₁ = 85°C |

⁽¹⁾ T₀, T₁ are thermistor's temperatures

$$\beta = \frac{R_0}{R_1} = \exp \left[\beta \left(\frac{1}{T_0} - \frac{1}{T_1} \right) \right], \text{ Temperatures in Kelvin}$$

Thermal- Mechanical Specifications

| Parameters | Min | Typ | Max | Units |
|--|--------|---------|------|--------|
| T _J Operating Junction Temperature Range | - 40 | | 150 | °C |
| T _{STG} Storage Temperature Range | - 40 | | 125 | |
| R _{thJC} Junction-to-Case | IGBT | | 0.20 | °C/ W |
| | Diode | | 0.39 | |
| R _{thCS} Case-to-Sink (Heatsink Compound Thermal Conductivity = 1 W/mK) | Module | | 0.06 | |
| Clearance (external shortest distance in air between two terminals) | 5.5 | | | mm |
| Creepage (shortest distance along external surface of the insulating material between 2 terminals) | 8 | | | |
| T Mounting torque to heatsink (3) | | 3 ± 10% | | Nm |
| Wt Weight | | 66 | | g (oz) |

(3) A mounting compound is recommended and the torque should be checked after 3 hours to allow for the spread of the compound. Lubricated threads

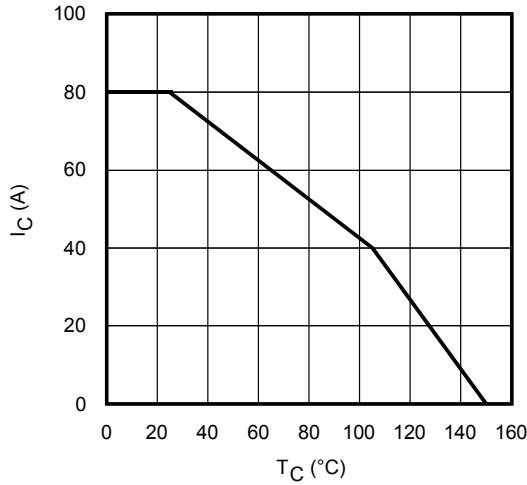


Fig. 1 - Maximum DC Collector Current vs. Case Temperature

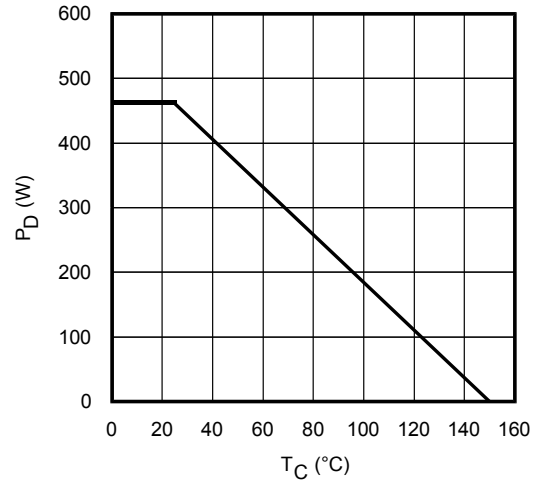


Fig. 2 - Power Dissipation vs. Case Temperature

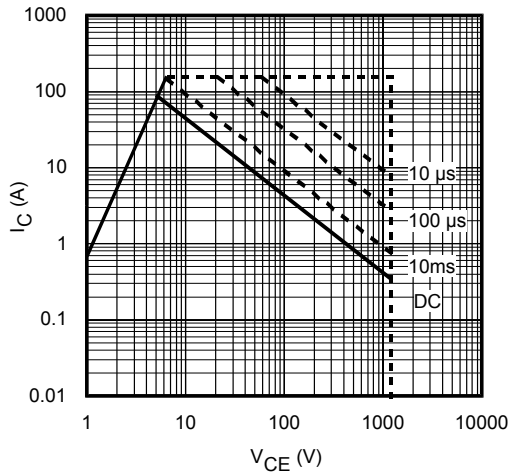


Fig. 3 - Forward SOA
 $T_C = 25^{\circ}C$; $T_J \leq 150^{\circ}C$

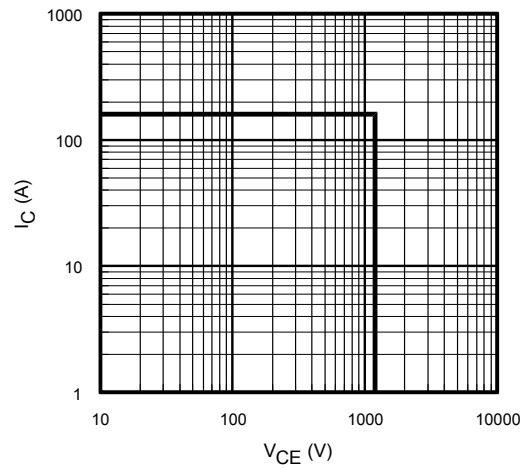


Fig. 4 - Reverse Bias SOA
 $T_J = 150^{\circ}C$; $V_{GE} = 15V$

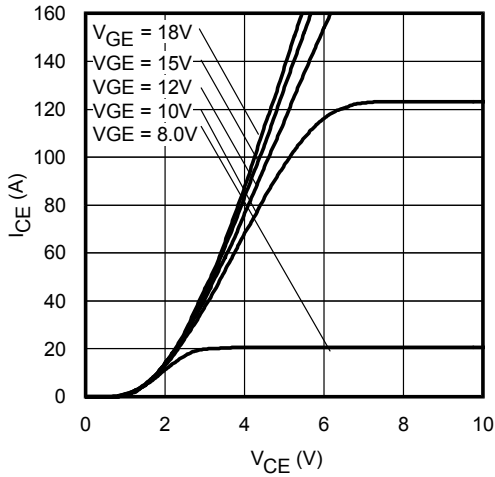


Fig. 5 - Typ. IGBT Output Characteristics
 $T_J = -40^\circ\text{C}$; $t_p = 80\mu\text{s}$

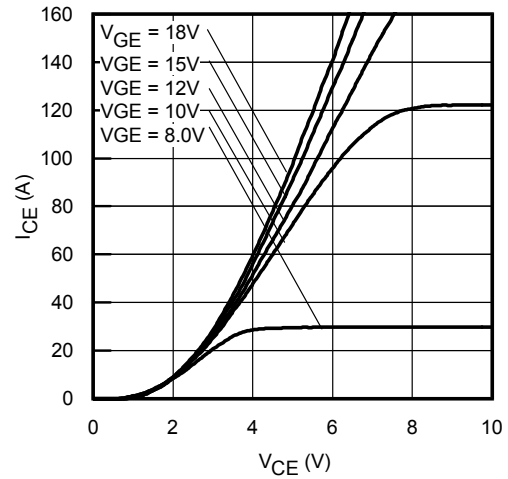


Fig. 6 - Typ. IGBT Output Characteristics
 $T_J = 25^\circ\text{C}$; $t_p = 80\mu\text{s}$

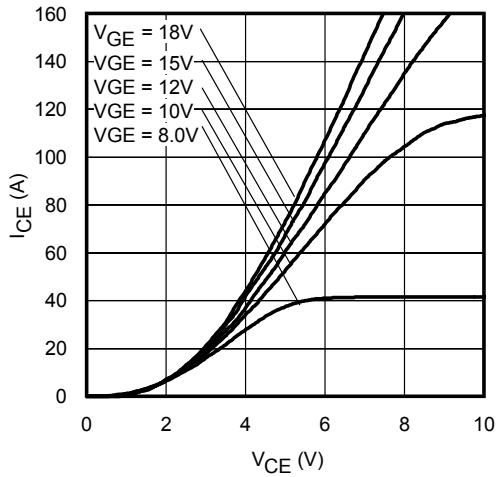


Fig. 7 - Typ. IGBT Output Characteristics
 $T_J = 125^\circ\text{C}$; $t_p = 80\mu\text{s}$

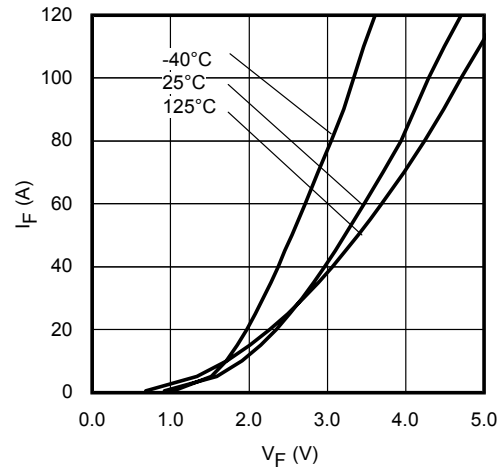


Fig. 8 - Typ. Diode Forward Characteristics
 $t_p = 80\mu\text{s}$

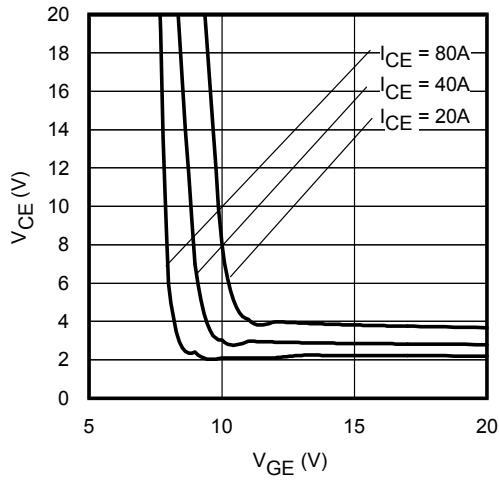


Fig. 9 - Typical V_{CE} vs. V_{GE}
 $T_J = -40^\circ\text{C}$

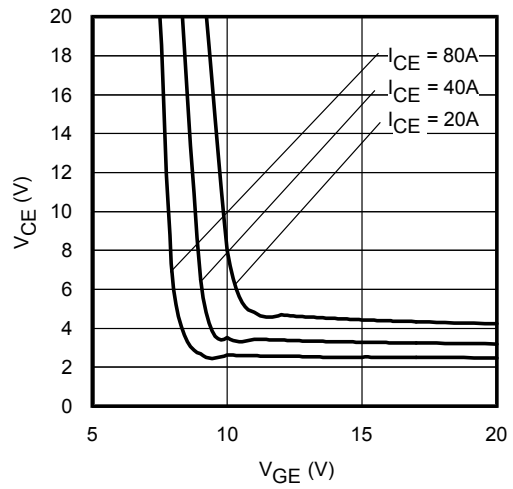


Fig. 10 - Typical V_{CE} vs. V_{GE}
 $T_J = 25^\circ\text{C}$

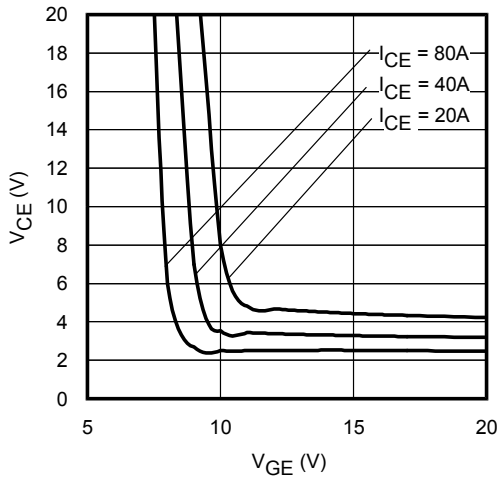


Fig. 11 - Typical V_{CE} vs. V_{GE}
 $T_J = 125^\circ\text{C}$

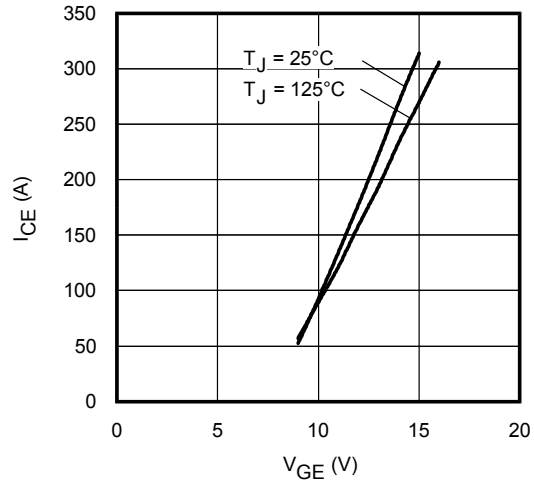


Fig. 12 - Typ. Transfer Characteristics
 $V_{CE} = 50\text{V}$; $t_p = 10\mu\text{s}$

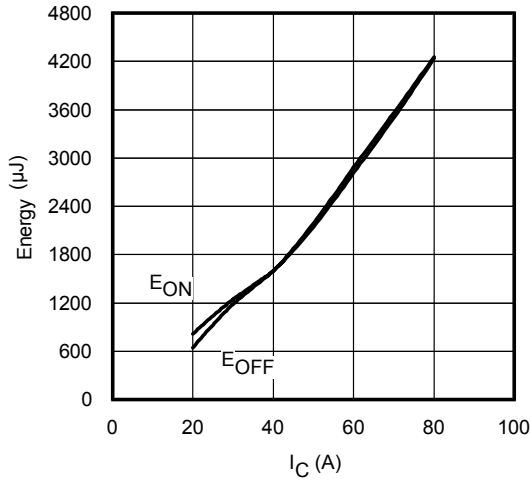


Fig. 13 - Typ. Energy Loss vs. I_C
 $T_J = 125^\circ\text{C}$; $L=250\mu\text{H}$; $V_{CE}=400\text{V}$
 $R_G=5\Omega$; $V_{GE}=15\text{V}$

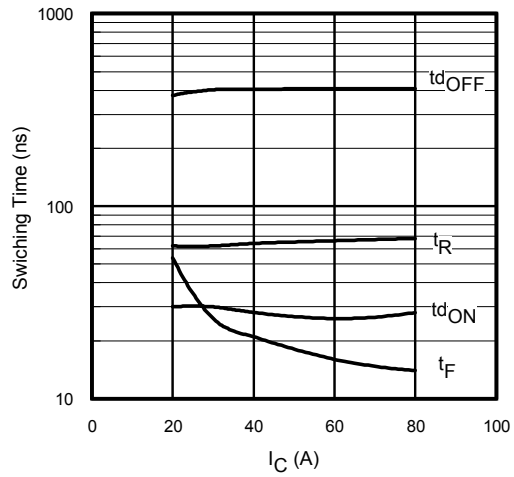


Fig. 14 - Typ. Switching Time vs. I_C
 $T_J = 125^\circ\text{C}$; $L=250\mu\text{H}$; $V_{CE}=400\text{V}$
 $R_G=5\Omega$; $V_{GE}=15\text{V}$

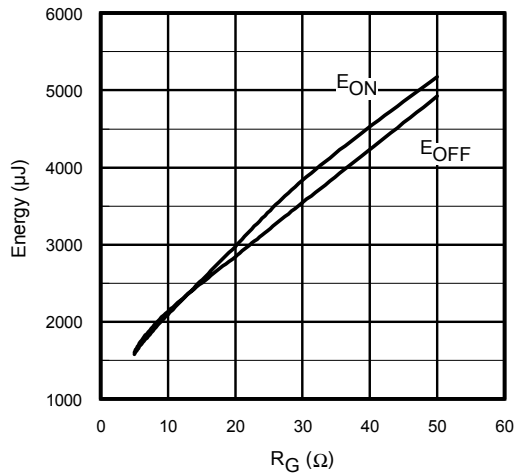


Fig. 15 - Typ. Energy Loss vs. R_G
 $T_J = 150^\circ\text{C}$; $L=250\mu\text{H}$; $V_{CE}=600\text{V}$
 $I_{CE}=40\text{A}$; $V_{GE}=15\text{V}$

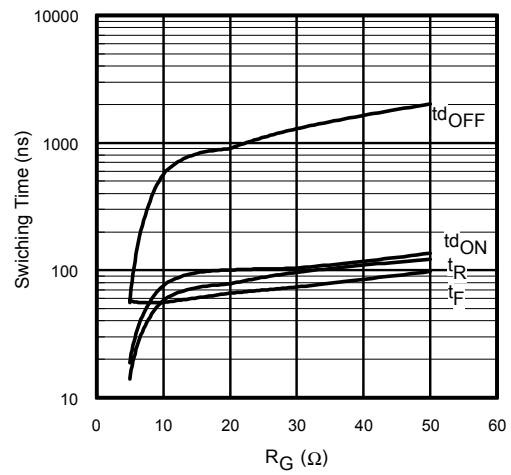


Fig. 16 - Typ. Switching Time vs. R_G
 $T_J = 150^\circ\text{C}$; $L=250\mu\text{H}$; $V_{CE}=600\text{V}$
 $I_{CE}=40\text{A}$; $V_{GE}=15\text{V}$

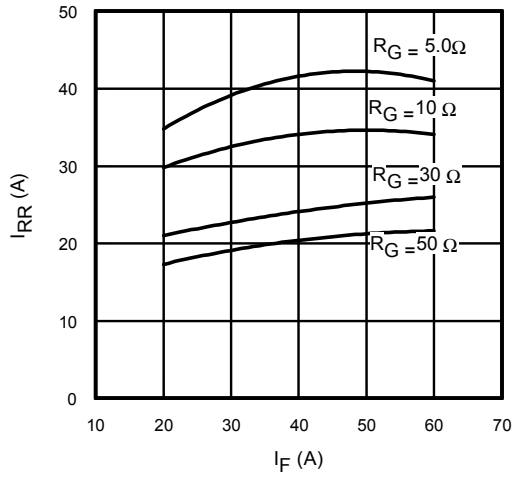


Fig. 17 - Typical Diode I_{RR} vs. I_F
 $T_J = 125^\circ\text{C}$

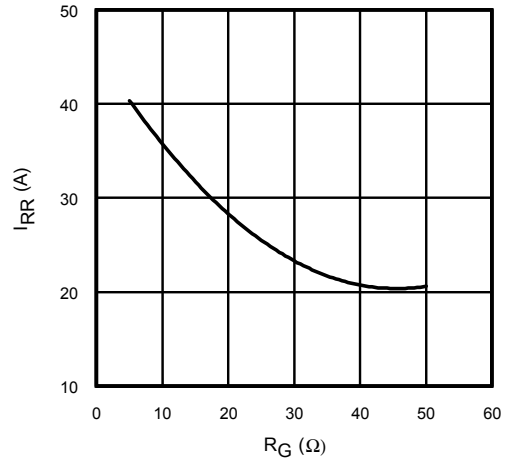


Fig. 18 - Typical Diode I_{RR} vs. R_G
 $T_J = 125^\circ\text{C}; I_F = 40\text{A}$

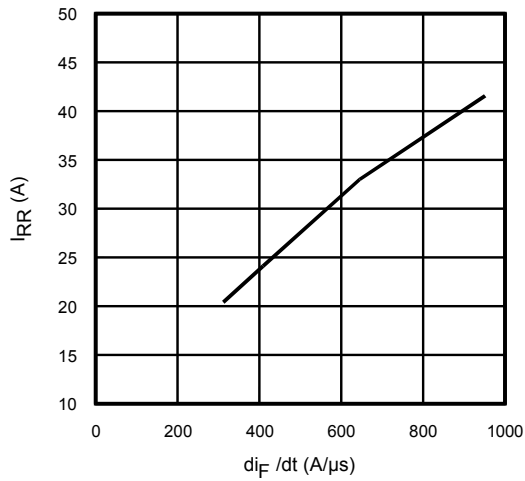


Fig. 19 - Typical Diode I_{RR} vs. di_F/dt
 $V_{CC} = 600\text{V}; V_{GE} = 15\text{V};$
 $I_{CE} = 40\text{A}; T_J = 125^\circ\text{C}$

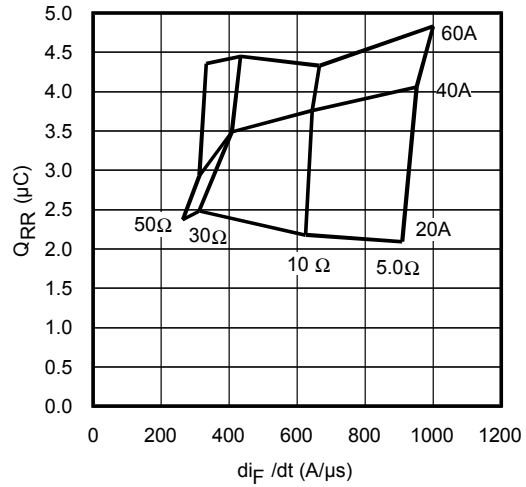


Fig. 20 - Typical Diode Q_{RR}
 $V_{CC} = 600\text{V}; V_{GE} = 15\text{V}; T_J = 125^\circ\text{C}$

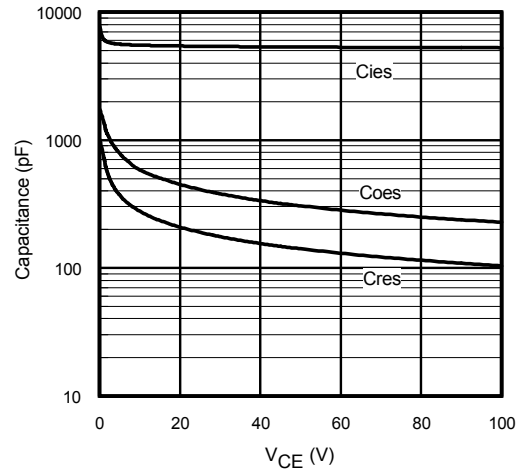


Fig. 21- Typ. Capacitance vs. V_{CE}
 V_{GE}= 0V; f = 1MHz

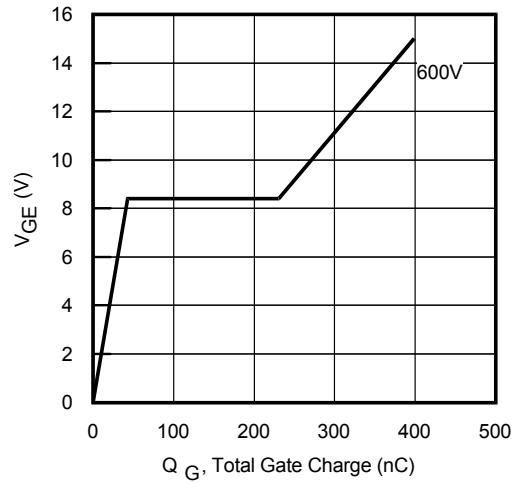


Fig. 22 - Typical Gate Charge vs. V_{GE}
 I_{CE} = 5.0A; L = 600μH

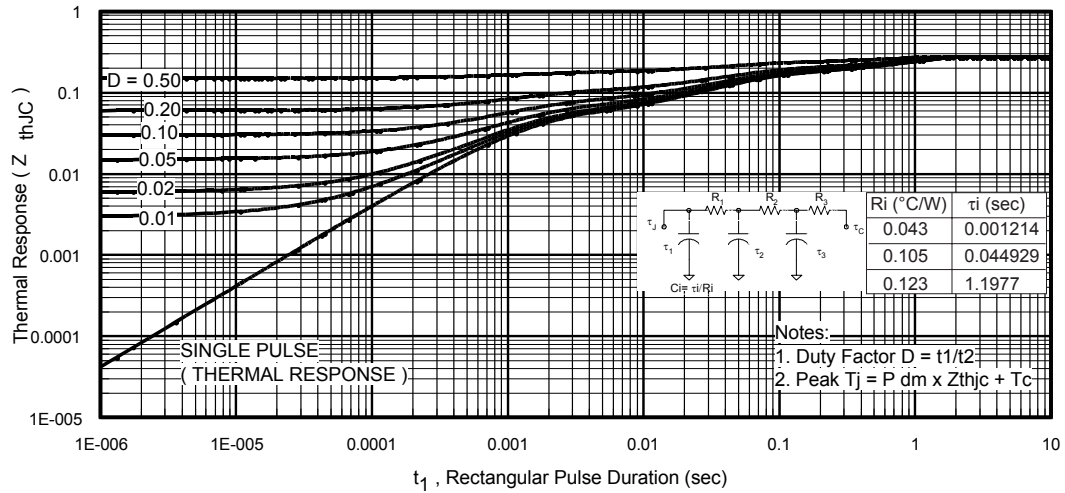


Fig 23. Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

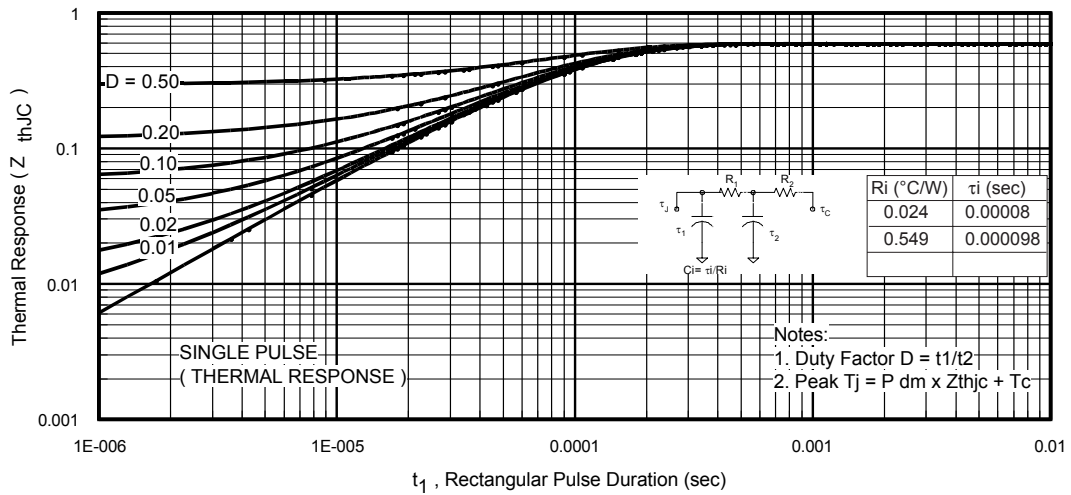


Fig 24. Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

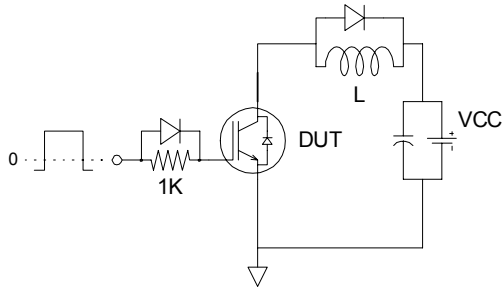


Fig. CT.1 - Gate Charge Circuit (turn-off)

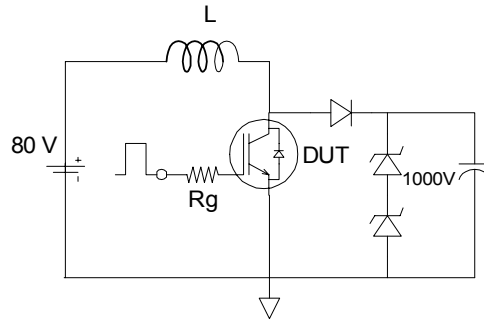


Fig. CT.2 - RBSOA Circuit

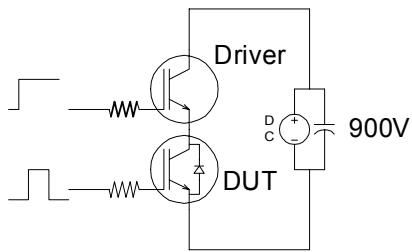


Fig. CT.3 - S.C. SOA Circuit

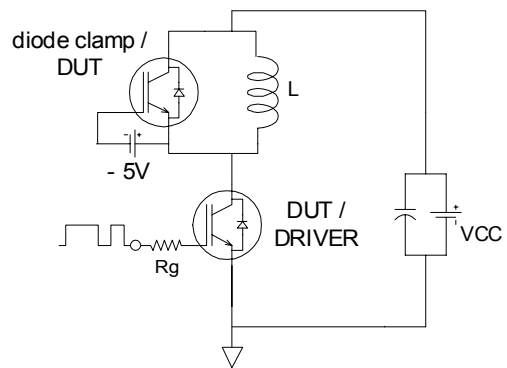
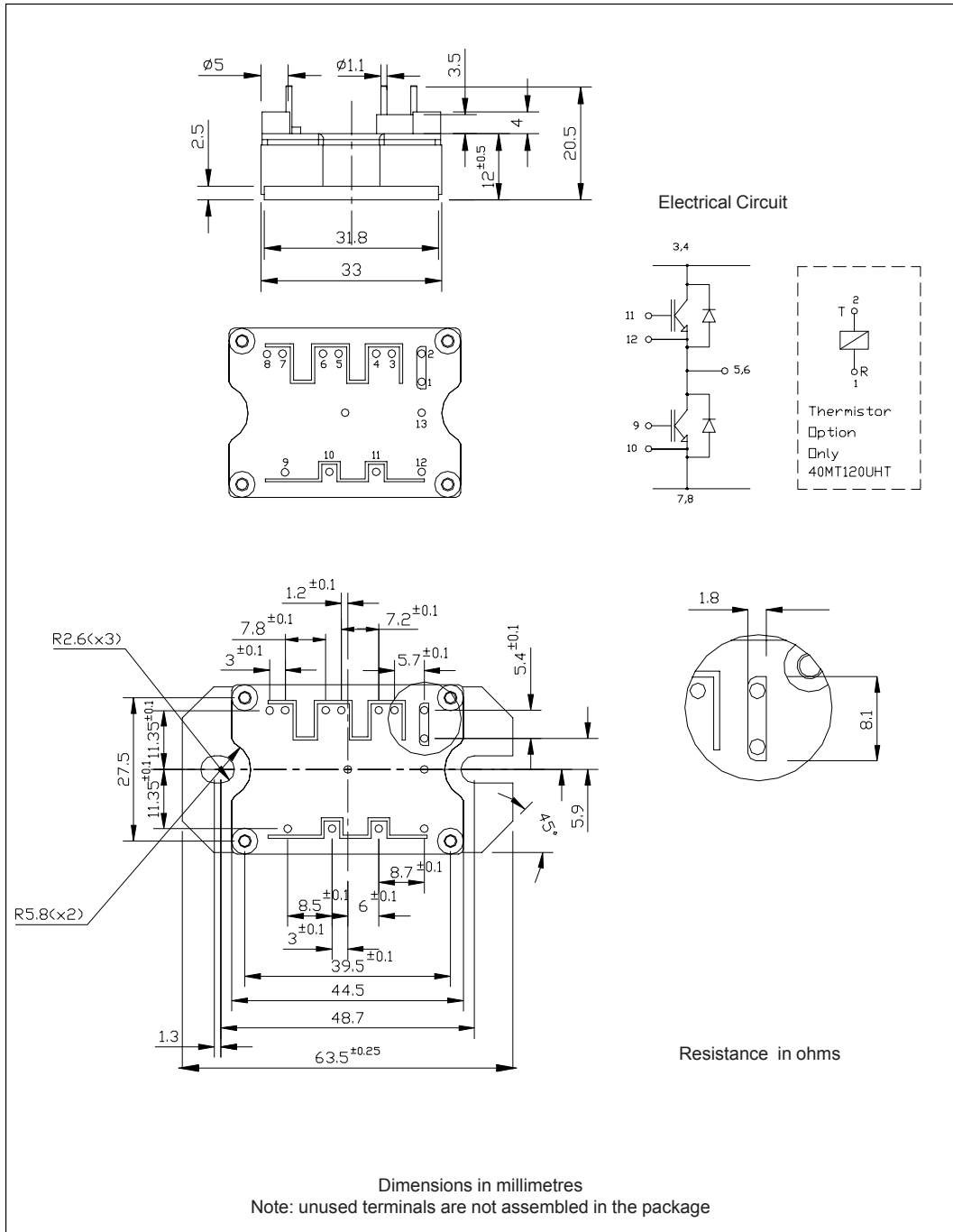


Fig. CT.4 - Switching Loss Circuit

Outline Table



Ordering Information Table

| Device Code | |
|-------------|---|
| 40 | MT |
| 120 | U |
| H | - |
| ① | ② |
| ③ | ④ |
| ⑤ | ⑥ |
| 1 | - Current rating (40 = 40A) |
| 2 | - Essential Part Number |
| 3 | - Voltage code (120 = 1200V) |
| 4 | - Speed/ Type (U = Ultra Fast IGBT) |
| 5 | - Circuit Configuration (H = Half Bridge) |
| 6 | - Special Option |
| | Empty = no special option T = Thermistor |

Data and specifications subject to change without notice.
 This product has been designed and qualified for Industrial Level.
 Qualification Standards can be found on IR's Web site.